
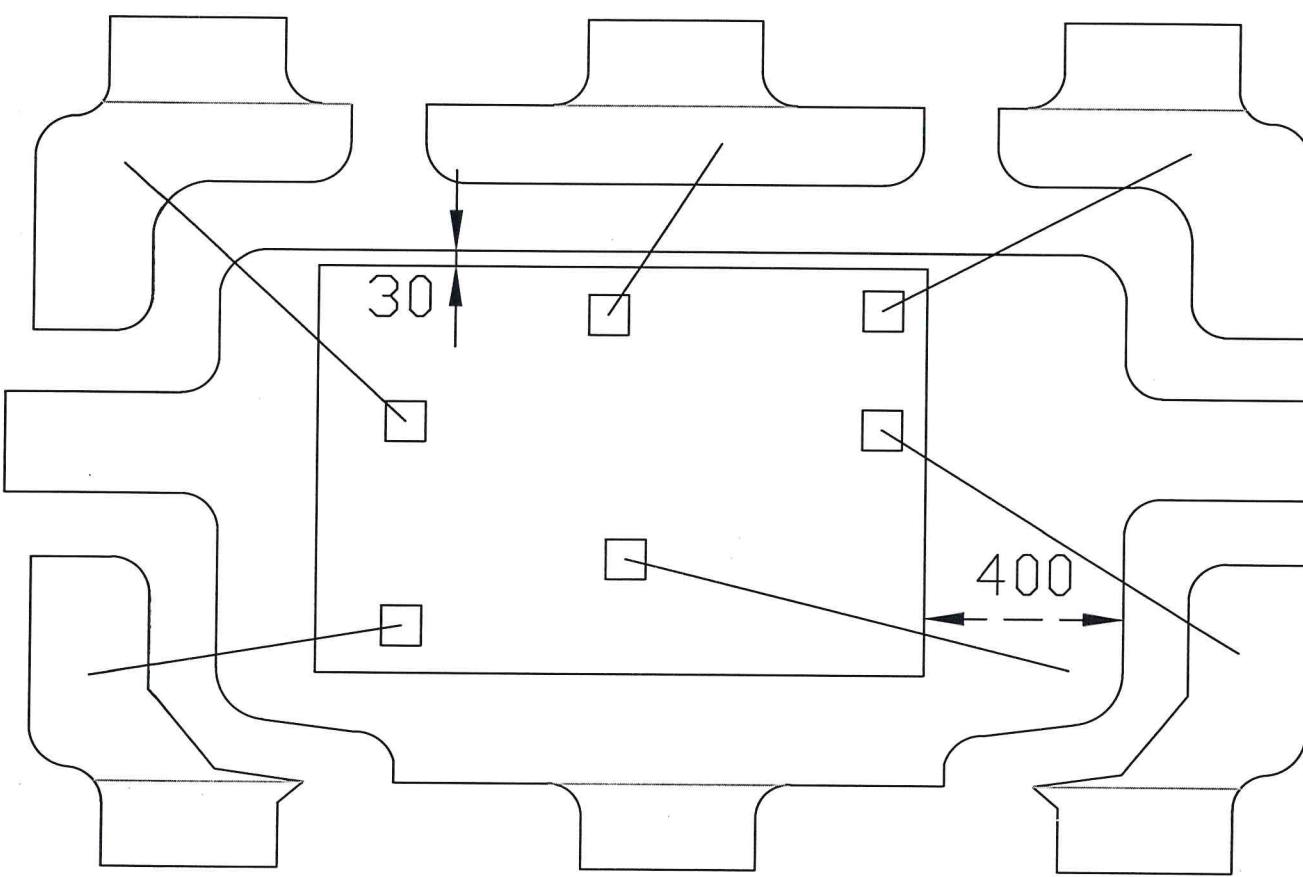
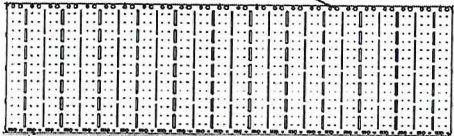


<div>池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD</div>				客户代码 Customer No.	008	线号 Drawing No.	HY-PX-008-779 A				
焊线图 Bonding Diagram				产品名称 Product Type	8023S		封装外型 PKG Type	SOT26 (14R)			
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)		LF载体尺寸 LF Pad Size			
合金丝 Ag	20	6	5551	842	407	首选(Preferred): CEL-1702HF 备选(Optional):		SOT23-6L-14R (42×72mil²) 1060*1820um²			
客户图号 Customer drawing NO.											
<div><div>4</div><div>5</div><div>6</div><div>3</div><div>2</div><div>1</div></div>											
框架传递方向(装片): L/F Direction (D/A): 椭圆孔				实物图: Chip photo:		特殊说明 Special Instructions: 产品8023S对应: 8R:HY-PX-008-676 A 12R:HY-PX-008-779 A					
											
注意: 基岛全镀银											
说明 Instructions	粘片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BFO (μm²)	最小焊盘间距 Min BPP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否足 Low-K IC Insulation	减薄厚度 (μm) Wafer Thickness
A芯: DIE A	导电胶 (conductivity) S210	HS5083	810*1221(μm²) 31.8*48.00(mil²)	80*80	236	2.5	否/NO	80	NA	否/NO	230
B芯: DIE B											
C芯: DIE C											
编制 Prepared by	张明俊 2024.7.10			制图日期 Create Date	2024/7/10		生效日期 Effective Date	客户确认签字/盖章: Customer Signature			
研发审核 R&D Check	张明俊 2024.7.10			产品工程审核 PE Check			批准 Approved by				
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